

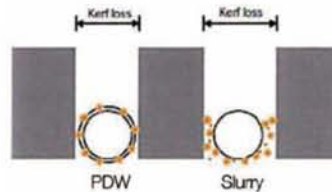
## PRECISION DIAMOND WIRE (PDW)



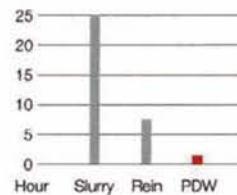
### Advantages

- High throughput & Superior cutting quality
  - Reduced process lead time and kerf loss
  - Enhanced flatness of cut materials and superior Warp, TTV and Bow values
- Applicable for thin wafer slicing - through uniform diamond grit
- Longer wire lifetime - Excellent diamond retention & no wire breakage
- Faster cutting speed - 3~10 times compared with slurry process
- Low cost and eco-friendly - Slurry free process

#### ■ Minimized kerf loss comparing to conventional method



#### ■ Process time



### For Silicon

For silicon slicing application, EHWA provides diamond wire in as 50um along with 120um. In realizing minimized kerf loss and superior cutting quality for high yield and utilization of thin wafer process, EHWA PDW will be the only solution.

EHWA PDW is easily adapted to other cutting systems in wider industries that would replace conventional cutting methods meeting customers' requirements for cutting quality and expectations for high throughput and cost savings

#### ■ Squaring



PDW Order code | 300-D50  
250-D50

#### ■ Slicing



PDW Order code | 90-D35

### EHWA DIAMOND IND. CO. LTD.

HEAD OFF. : 374, Nambu-daero, Osan-si,  
Gyeonggi-do, 18145, Korea  
Tel : (82-31)370-9000  
Fax : (82-31)374-9235

SALES DEPT. Tel : (82-31)370-0500  
Fax : (82-31)370-0605

INTERNET : <http://www.ehwadia.co.kr>  
E-MAIL : [semi@ehwadia.co.kr](mailto:semi@ehwadia.co.kr)





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## For Sapphire

EHWA PDW is widely accepted in slicing and cropping process for 2", 4" and 6" sapphire wafer preparation and it is expanding its presence in 8" sapphire wafer preparation process. Compared to Resin-coated diamond Wire, EHWA PDW has better thermal stability, longer lifetime and allows fast cutting time resulting in high throughput.

## SPECS for PDW

	core material <sup>1)</sup>			diamond size (um)	kerf loss(um)	concentration <sup>3)</sup> & spool <sup>4)</sup> availability
	Order Code	diameter (Φ,um)	WBS (N) <sup>2)</sup>			
Mono-/Poly-Si Wafering	50-D-9	50	10	5~10	60~70	We can provide wire according to the customer's request
	60-D-10	60	12	6~12	70~80	
	70-D-10	70	18	8~12	80~90	
	80-D-12	80	21	8~16	90~100	
	90-D-12	90	23	8~16	100~110	
	120-D-15	120	40	10~20	140~145	
Sapphire Ingot Wafering	160-D35	160	65	30~40	220~240	
	180-D35	180	85	30~40	235~255	
	180-D45	180	85	40~50	245~255	
Si Squaring/ Sapphire Cropping	200-D35	200	110	30~40	260~280	
	250-D35	250	180	30~40	310~330	
	250-D50			40~60	340~360	
	300-D50	300	240	40~60	390~410	

- 1) high-quality piano wire, 2) wire breaking strength  
3) low, middle, high concentration with continuous quality  
4) lengths to 5, 10, 20, 30km, 50km, +100km

